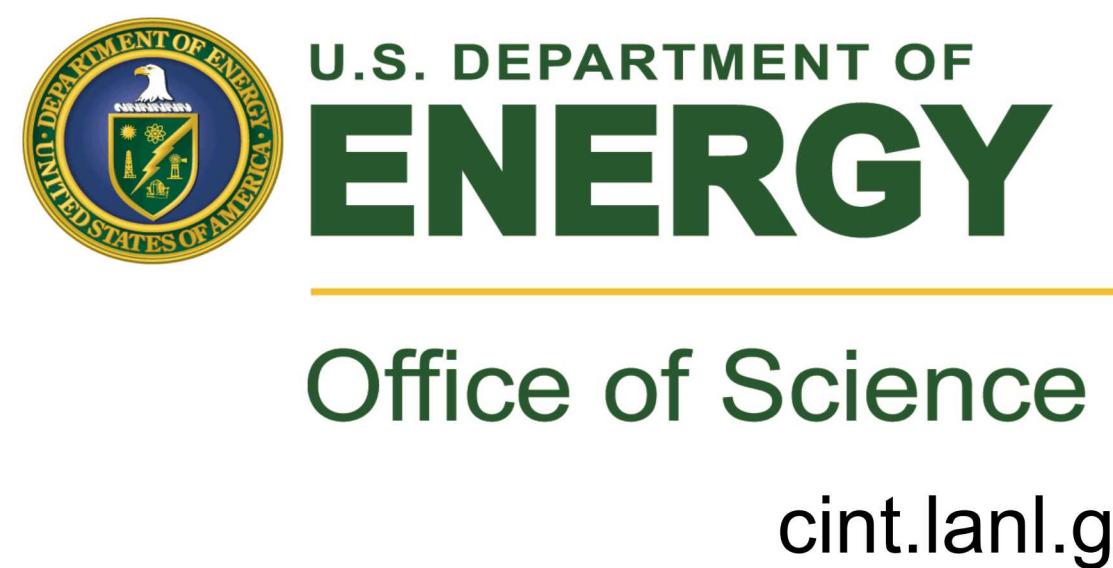




Yield Improvement of SiV⁻ Color Centers in Diamond via Silicon/Carbon Sequential Implantation

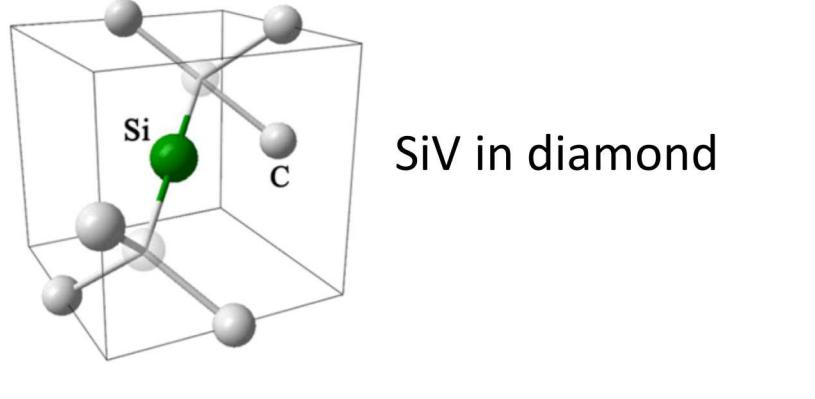
W. J. Hardy, D. Lee and E. Bielejec
Sandia National Laboratories, Albuquerque, NM



Motivation

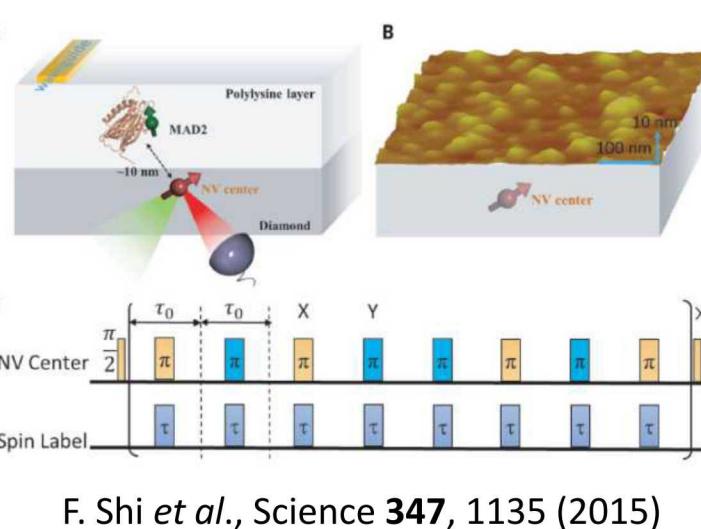
Why Color Centers in Diamond?

- Color centers (defects) in diamond include NV⁻, SiV plus many more...
- Wide range of application from metrology to quantum computation



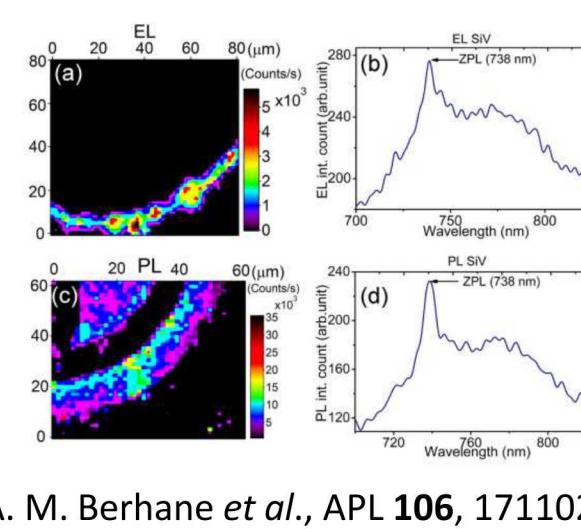
I. Aharonovich *et al.*, Rep. Prog. Phys. 74,076501 (2011)

Single-protein spin resonance



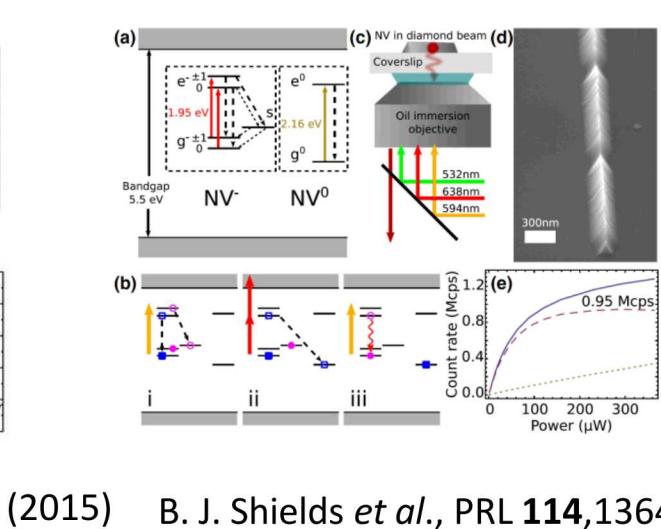
F. Shi *et al.*, Science 347, 1135 (2015)

Electrically driven SiV



A. M. Berhane *et al.*, APL 106, 171102 (2015)

Readout of single NV spin



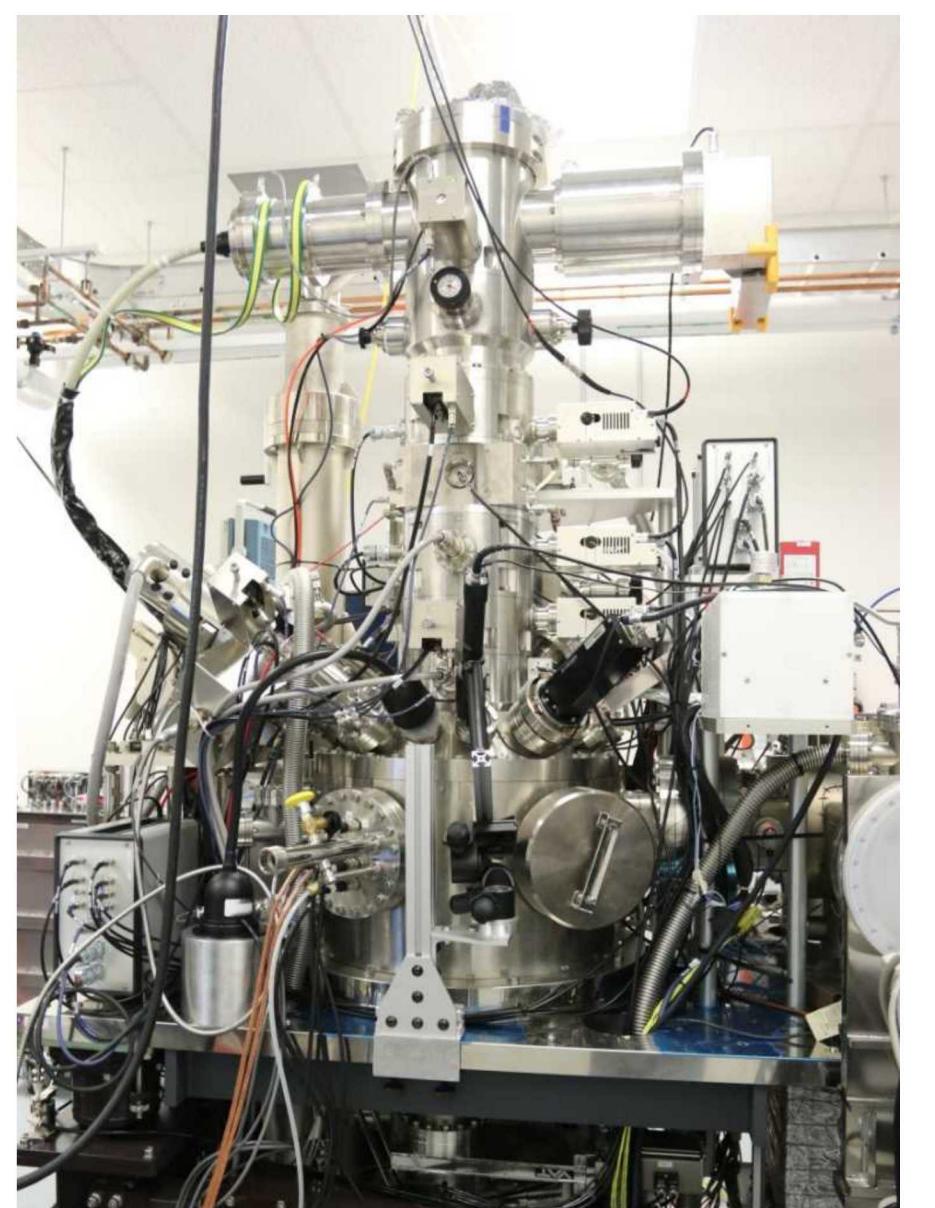
B. J. Shields *et al.*, PRL 114,136402 (2015)

- Key question → How to produce a single color center where you want it?

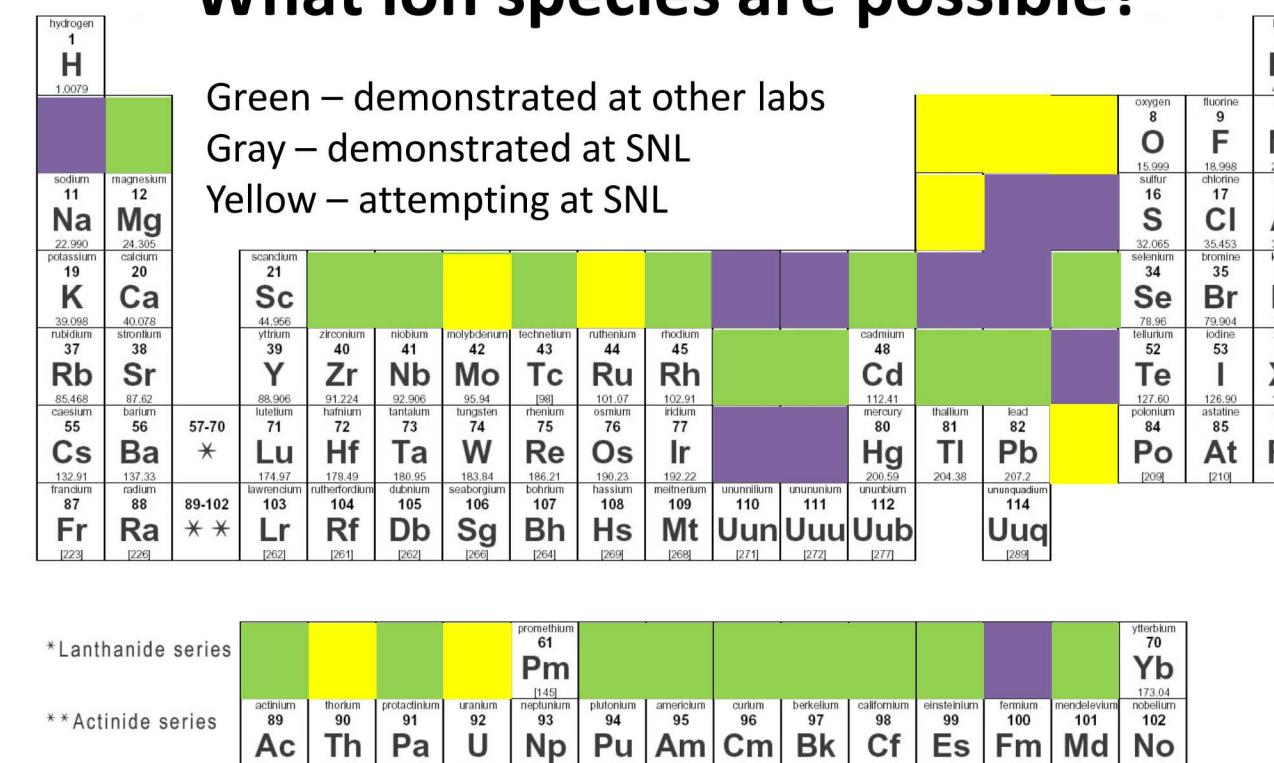
Nanoscale Top-Down Ion Implantation

nanolplanter

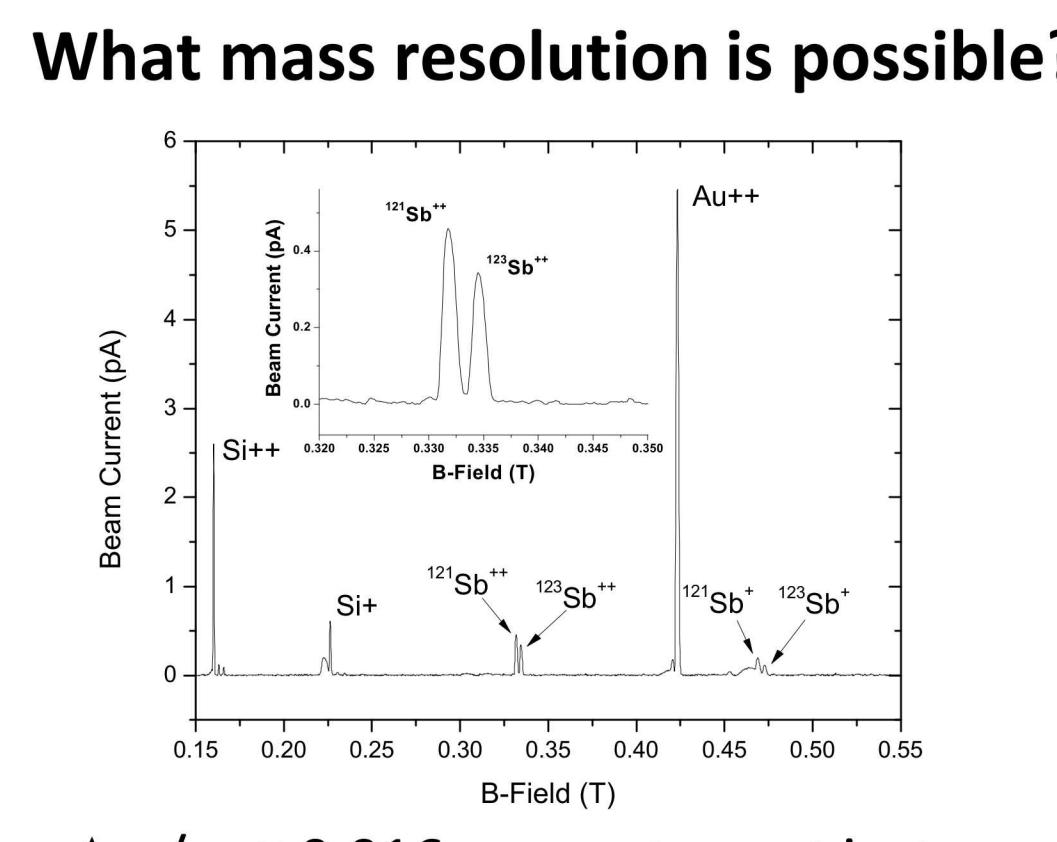
- Focused ion beam system (FIB) → nm beam spot size on target
- ExB Filter (Wien Filter) → Multiple ion species
- Fast blanking and chopping → Single ion implantation
- Direct-write lithography → nm targeting accuracy



What ion species are possible?

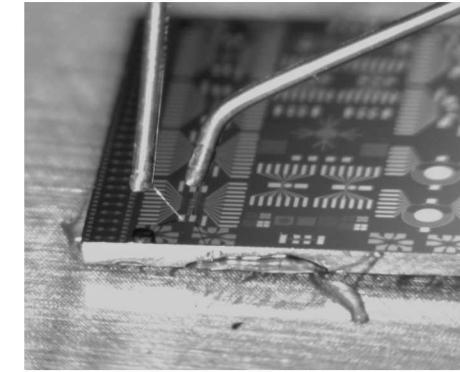


~1/3 the periodic table are available



$\Delta m/m \sim 0.016$, separates out isotopes of Sb and Si in this AuSiSb source

Direct write platform and in-situ electrical probes

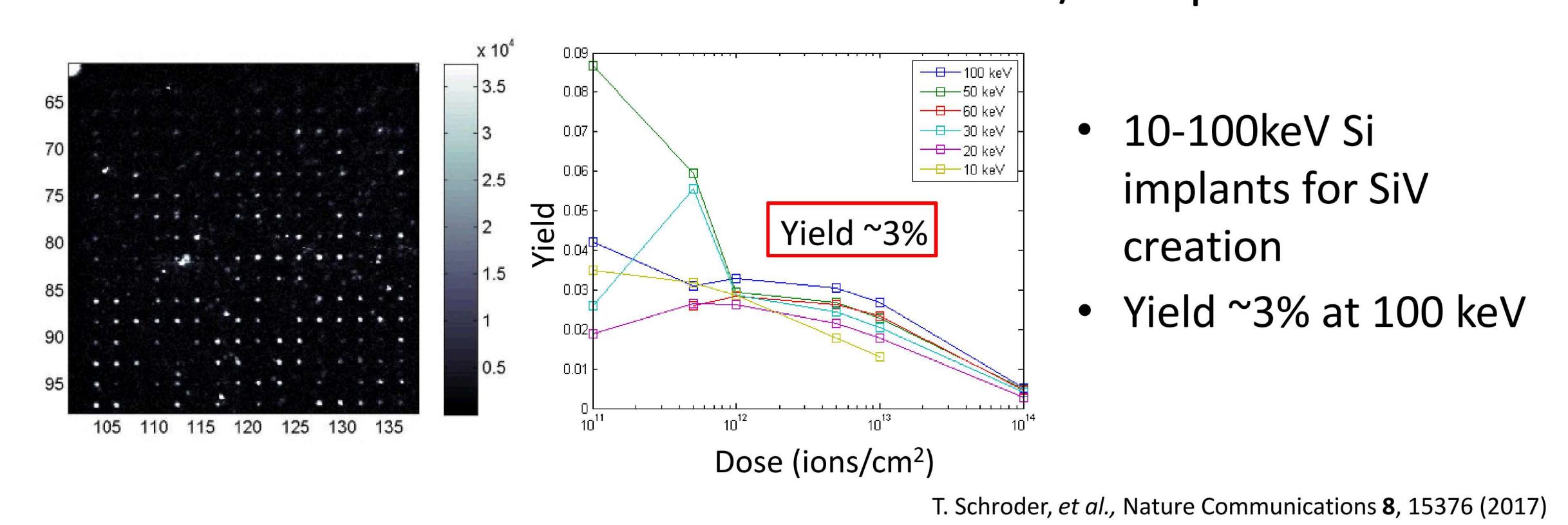


- In-situ electrical probes for measurement of ion strikes as they occur
- Low temperature stage
- Built-in lithography software (Raith ELPHY Plus) with sub-nm resolution

RAITH
NANOFABRICATION

SiV Yield – How to improve?

Yield Testers

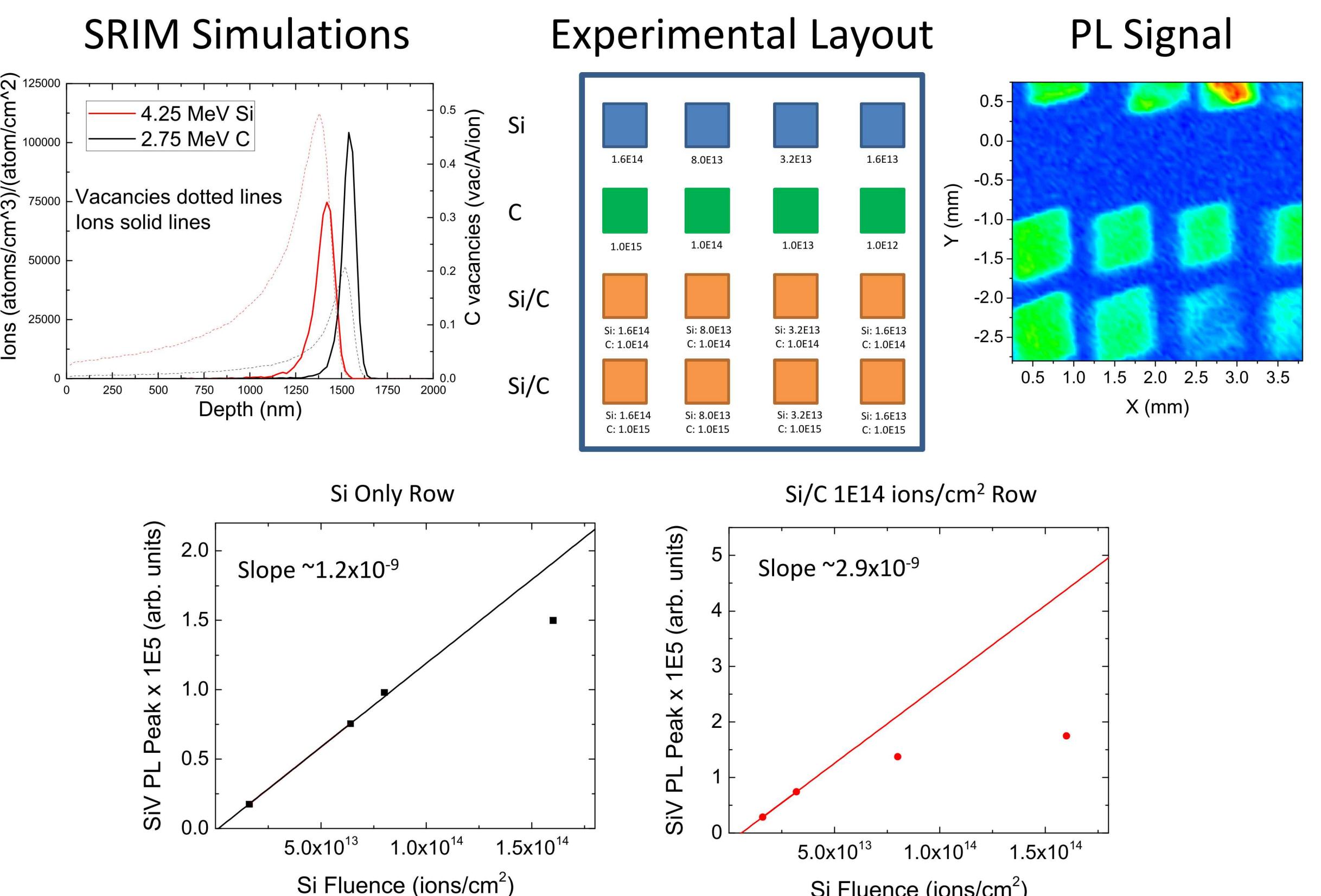


How to Improve the Yield of the SiV centers?

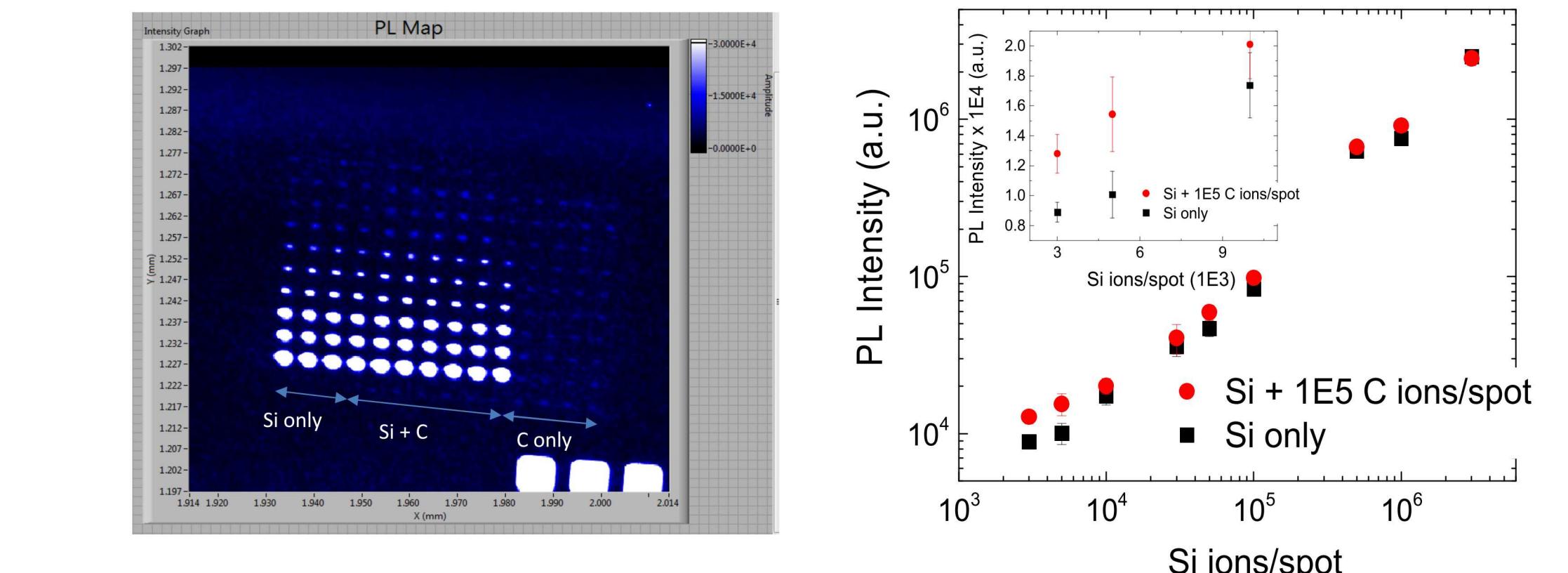
What is limiting the yield? Vacancies, charge state of the defect?

Yield → Electrical Charge State Control
Localized Band Bending via Boron Doping
Sequential Implantation to create excess vacancies

Sequential Si and C Implantation – mm sized areas



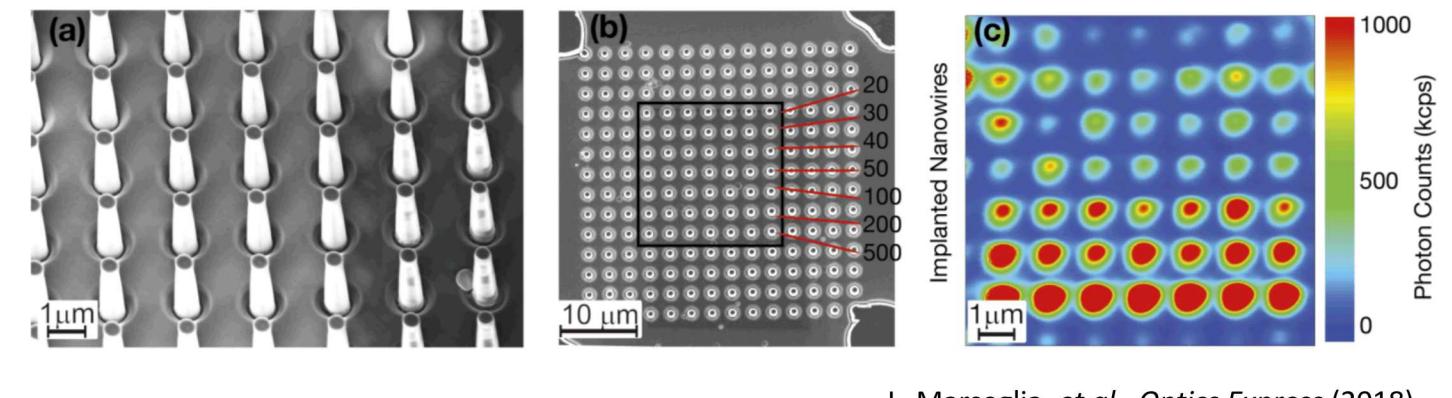
Sequential Si and C Implantation – μm sized areas



Conclusions and Future Directions

Nanoscale Top-down Ion Implantation

- Demonstrated focused ion beam implantation for application in single atom devices.



SiV Formation Yield

- Yield needs to be understood and/or improved as a function of color center type and implantation depth

→ Demonstrated a technique to extract yield numbers

- Yield can be improved for a given depth with pre-irradiation to damage the localized areas (excess vacancies)

→ Experiments demonstrate up to 2.4x improvement with sequential carbon implantation. C source development underway for the nanolplanter.

Focused Ion Beam Capability at SNL

MicroOne (Tandem Accelerator)



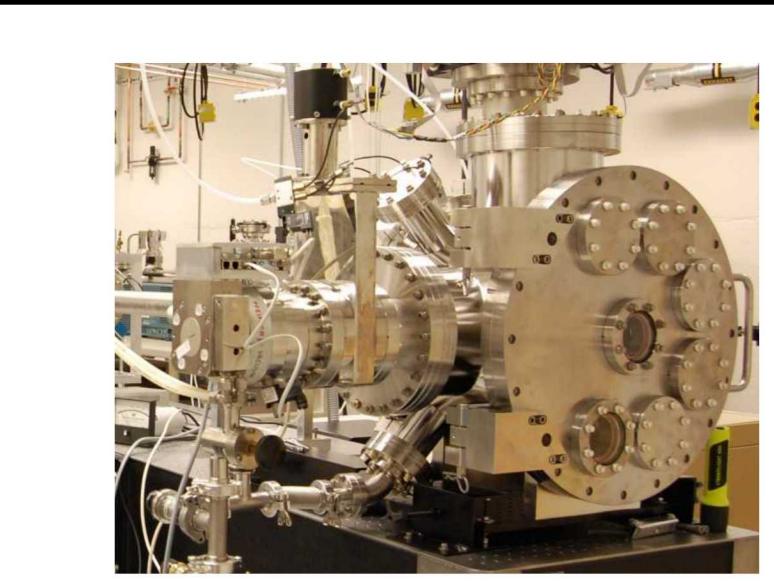
- Light to Heavy Ions – H to I
- Energy range from ~800 keV to >70 MeV
- Spot size as small as ~800 nm

Light Ion Microbeam (Pelletron)



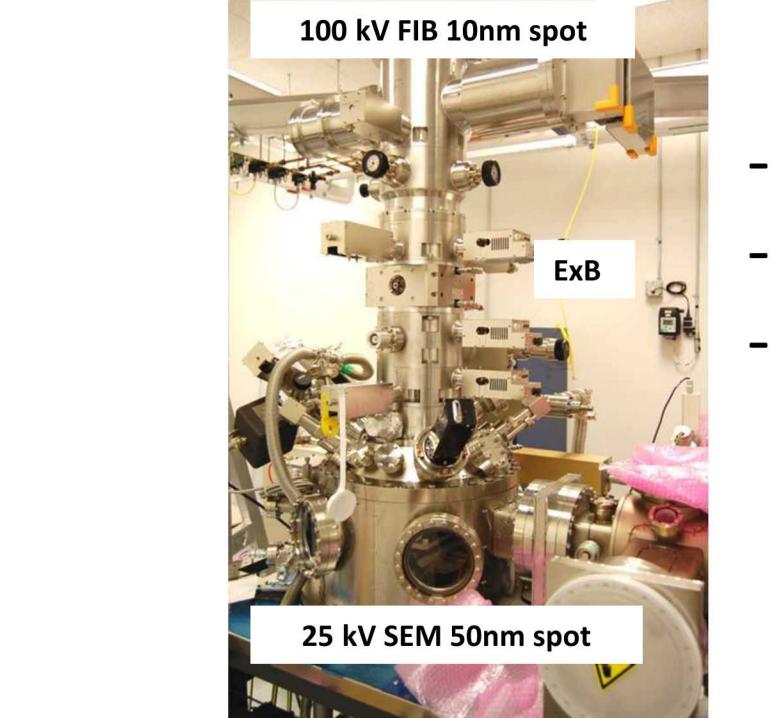
- Light Ions – H, He3, He4, N
- Energy range from ~300 keV to 3 MeV
- Spot size as small as ~150 nm

NanoBeamLine (HVEE Implanter)



- Light to Heavy Ions – H to Xe
- Energy range from ~10 keV to 350 keV
- Spot size as small as ~800 nm

nanolplanter



- Liquid Metal Ion Sources – Au, Si, Sb, P, Li, etc...
- Energy range from 10 keV to 200 keV
- Spot size as small as ~10 nm